

EVASOL

J3-MFJ-3

Sn-Ag-Cu series

Lead free flux cored solder wire

- MIL-RMA, JIS-A, IPC-ROL1 type lead free type flux cored wire solder.
- Good wettability and low flux spattering at soldering.

Table .Characteristics

Items	Characteristics	Test method
Alloy composition (%)	Sn:Balance, Ag: 3.0 ± 0.1 , Cu: 0.5 ± 0.05	Allowable impurity level is based on JIS Z 3282.
Solidus temperature(°C)	217	DSC(Differential Scanning Calorimetry)
Liquidus temperature(°C)	220	
Flux content (%)	2.7~3.3	JIS Z 3197 8.1.2
Halide content*(%)	0.08~0.14	JIS Z 3197 8.1.4.2.1
Copper mirror test	No corrosion	JIS Z 3197 8.4.2
Copper plate corrosion test	No corrosion	JIS Z 3197 8.4.1
Insulation resistance test(Ω)	More than 5.0×10^8	JIS Z 3197 8.5.3 JIS type, 85°C-85%RH, 168h, measured with DC100v inside of chamber
Migration test	No migration	JIS Z 3197 8.5.3 JIS type, 85°C-85%RH, 1000h, applied with DC48v, visual check
Aqueous solution resistance test(Ωm)	More than 1000	JIS Z 3197 8.1.1
Dryness test	Passed	JIS Z 3197 8.5.1
Spreading factor test(%)	More than 75	JIS Z 3197 8.3.1.1
Remarks	JIS Z 3282:2006 Solders-Chemical compositions and forms JIS Z 3197:1999 Testing method for soldering fluxes	

*Halide content is calculated Br to Cl. Cl is not contained.